

Application No. 10/786,578
Amendment dated October 17, 2005
Reply to Office Action of July 8, 2005

Docket No. CM06657LL

Amendment to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the application.

Listing of Claims:

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1. (original) An apparatus for attaching a solid solder element to a solderable substrate, comprising:

an adhesive material applied to a portion of the solid solder element so as to overlap with the solderable substrate outside of a predefined area reserved for subsequent component placement, the adhesive material immobilizing the solid solder element during reflow.

Claims 2-3 (canceled)

4. (original) An interface apparatus for component attachment, comprising:

a solderable substrate;

a solid solder element; and

an adhesive material for coupling the solid solder element to the solderable substrate, the adhesive material overlapping the solderable substrate and the solid solder element, the adhesive material cured so as to immobilize the solid solder element; and

the component subsequently being coupled to the solderable substrate via the solid solder element during a reflow process.

5. (original): The interface apparatus of claim 4, wherein the component is at least one of mechanical, electrical, and electro-mechanical components.

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6. (original): The interface apparatus of claim 4, wherein the adhesive material is characterized by a predetermined application viscosity, predetermined volume reduction during the reflow process, retention of adhesive qualities during the reflow process, and an inability to mix with the solid solder element during the reflow process.

7. (original) An interface apparatus for component attachment, comprising:
a solderable substrate;
a solid solder element; and
an adhesive material having predetermined geometry and adhesive properties cured so as to couple the solid solder element to the solderable substrate; and
the component subsequently being coupled to the solderable substrate via the solid solder element during a post cure reflow process during which the adhesive material maintains its geometry and adhesive properties.